

### SMA/DO-214AC

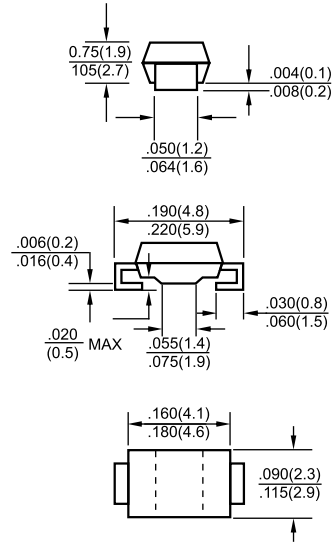


### Features

- ✧ For surface mounted application
- ✧ Glass passivated junction chip
- ✧ Built-in strain relief, ideal for automated placement
- ✧ Plastic material used carries Underwriters Laboratory Classification 94V-0
- ✧ Fast switching for high efficiency
- ✧ High temperature soldering: 260 °C / 10 seconds at terminals

### Mechanical Data

- ✧ Cases: Molded plastic
- ✧ Terminals: Pure tin plated, Lead free.
- ✧ Polarity: Indicated by cathode band
- ✧ Packing: 12mm tape
- ✧ Weight: 0.064 gram



Dimensions in inches and (millimeters)

### Maximum Ratings and Electrical Characteristics

Rating at 25 °C ambient temperature unless otherwise specified.

Single phase, half wave, 60 Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Type Number	Symbol	FS 2AA	FS 2BA	FS 2DA	FS 2GA	FS 2JA	FS 2KA	FS 2MA	Units
Maximum Recurrent Peak Reverse Voltage	$V_{RRM}$	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	$V_{RMS}$	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	$V_{DC}$	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current See Fig. 1 @ $T_L=100^\circ\text{C}$	$I_{(AV)}$	1.5							A
Peak Forward Surge Current, 8.3 ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	$I_{FSM}$	50							A
Maximum Instantaneous Forward Voltage @ 1.5A	$V_F$	1.3							V
Maximum DC Reverse Current @ $T_A=25^\circ\text{C}$ at Rated DC Blocking Voltage @ $T_A=125^\circ\text{C}$	$I_R$	5 200							uA uA
Maximum Reverse Recovery Time ( Note 1 )	$T_{rr}$	150			250	500		nS	
Typical Junction Capacitance ( Note 2 )	$C_j$	50							pF
Typical Thermal Resistance ( Note 3 )	$R_{\theta JA}$ $R_{\theta JL}$	55 18							$^\circ\text{C} / \text{W}$
Operating Temperature Range	$T_J$	-55 to +150							$^\circ\text{C}$
Storage Temperature Range	$T_{STG}$	-55 to +150							$^\circ\text{C}$

- Notes:
1. Reverse Recovery Test Conditions:  $I_F=0.5\text{A}$ ,  $I_R=1.0\text{A}$ ,  $I_{RR}=0.25\text{A}$
  2. Measured at 1 MHz and Applied  $V_R=4.0$  Volts
  3. Thermal Resistance from Junction to Ambient and Junction to Lead Mounted on P.C.B. with 0.2"x0.2" ( 5.0 x 5.0 mm ) Copper Pad Areas.

### RATINGS AND CHARACTERISTIC CURVES (FS2AA THRU FS2MA)

FIG.1- MAXIMUM FORWARD CURRENT DERATING CURVE

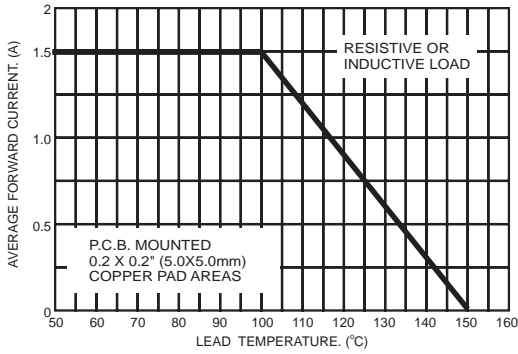


FIG.2- TYPICAL REVERSE CHARACTERISTICS

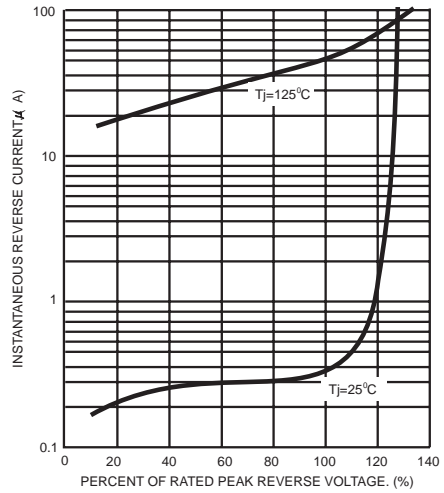


FIG.3- MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

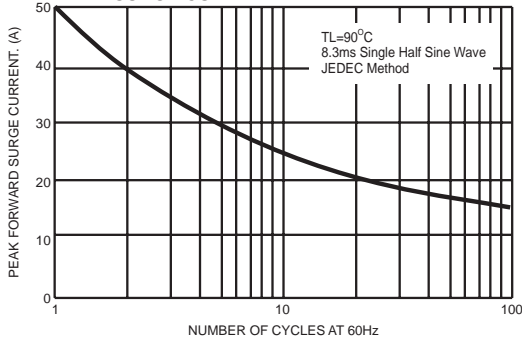


FIG.5- TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS PER LEG

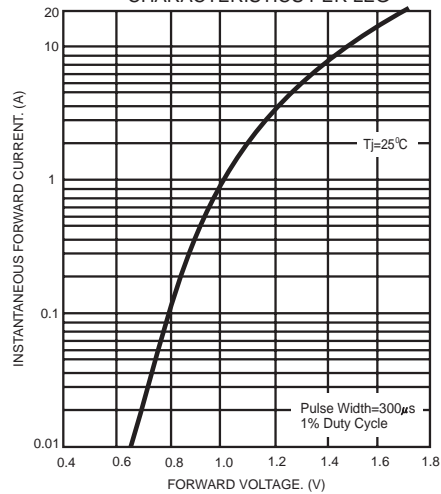


FIG.4- TYPICAL JUNCTION CAPACITANCE

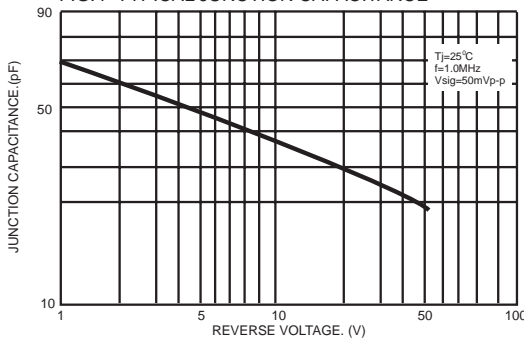


FIG.6- REVERSE RECOVERY TIME CHARACTERISTIC AND TEST CIRCUIT DIAGRAM

